

Serial No. 09/754,133

IN THE CLAIMS:

Please amend claims 24, 26, 29 and 31 as follows:

*Sub 1*  
24. (Amended) A method of manufacturing a circuit board comprising a plurality of wiring patterns and a plurality of protrusions located at desired locations on the wiring patterns on a substrate, wherein said method comprises simultaneously and unitarily forming the wiring patterns and the protrusions.

*B2*  
26. (Amended) The method of manufacturing a circuit board as defined in Claim 25 further comprising:

forming a first groove on a film, the first groove having a bottom surface;

forming a second groove at a predetermined location in the first groove;

filling conductive material into the first and the second grooves;

transferring the filled conductive material to the board; and  
firing the transferred conductive material.

*sub* 29. (Amended) A method of manufacturing a semiconductor device comprising:

*BZ* (a) simultaneously and unitarily forming a first plurality of wiring patterns and a second plurality of protrusions at desired locations on the wiring patterns on a circuit board; and

(b) coupling electrically the protrusions on said circuit board and electrodes on a semiconductor chip component.

*sub* 31. (Amended) The method of manufacturing a semiconductor device as defined in Claim 30 wherein forming the wiring patterns and the protrusions of the same conductive material comprises:

*BZ* forming a first groove on a film, the first groove having a bottom surface;

forming a second groove at a predetermined location in the first groove;

filling conductive material into the first and the second grooves;

transferring the filled conductive material onto the circuit board; and

firing the transferred conductive material.